

IN THE CLAIMS

Claims 1-33 (Canceled).

34 (New). A method of making a stencil for depositing material in the manufacture of semiconductor devices comprising:

forming a plurality of segmental annular openings in a stencil plate to define a central portion of the plate and a plurality of spokes connecting said central portion to the rest of said plate between adjacent segmental annular openings.

35 (New). The method of claim 34 including using a plate having a thickness from about 3 to about 10 mils.

36 (New). The method of claim 34 including forming said spokes to have a length of about 1 mil.

37 (New). The method of claim 34 including forming said central portion in a circular shape.

38 (New). The method of claim 34 including forming at least four openings and at least four spokes.